



## HIRP1608XC09-H5

### SMD Type 800nm Infrared Emitter

#### Features

- Small double-end package
- Viewing Angle =  $\pm 37.5^\circ$
- High reliability
- Good spectral matching to Si photo detector
- RoHS compliance

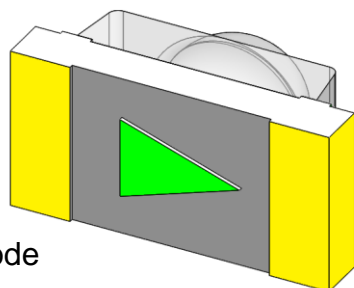
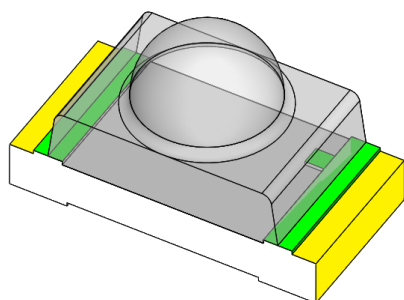
#### Applications

- Infrared sensor

#### Description

The HIRP1608XC09-H5 is a GaAlAs infrared LED housed in a miniature SMD package. The device has a peak wavelength of 800nm LED spectrally matched with phototransistor or photodiode.

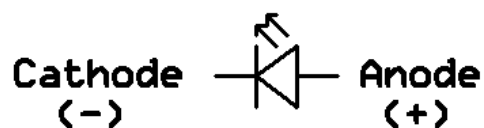
#### Package Outline



Cathode

Anode

#### Schematic





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### Absolute Maximum Rating at 25°C

Symbol	Parameters	Ratings	Units	Notes
I <sub>F</sub>	Continuous Forward Current	70	mA	
I <sub>FP</sub>	Peak Forward Current	1	A	1
V <sub>R</sub>	Reverse Voltage	5	V	
T <sub>opr</sub>	Operating Temperature	-40 ~ +85	°C	
T <sub>stg</sub>	Storage Temperature	-40 ~ +100	°C	
T <sub>sol</sub>	Soldering Temperature	260	°C	2
P <sub>D</sub>	Power Dissipation at(or below) 25°C Free Air Temperature	140	mW	

### Electro-Optical Characteristics *TA = 25°C (unless otherwise specified)*

#### Optical Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
I <sub>e</sub>	Radiant Intensity	I <sub>F</sub> =20mA	2.5	4.7	-	mW/sr	
		I <sub>F</sub> =70mA	-	17	-		
λ <sub>p</sub>	Peak Wavelength	I <sub>F</sub> =20mA	-	800	-	nm	
Δλ	Spectral Bandwidth	I <sub>F</sub> =20mA	-	25	-	nm	
θ <sub>1/2</sub>	Angle of Half Intensity	I <sub>F</sub> =20mA	-	±37.5	-	deg	

#### Electrical Characteristics

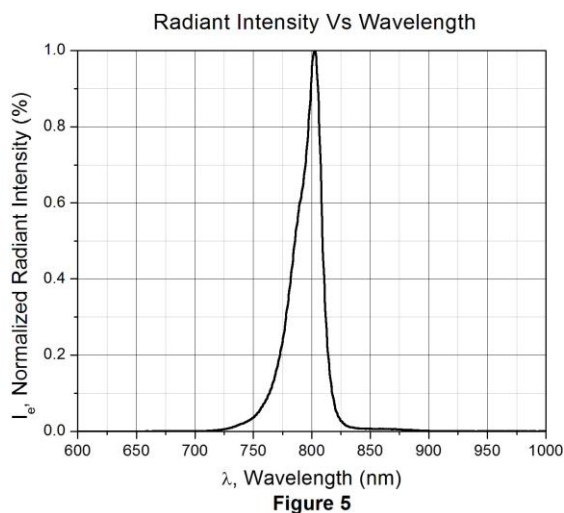
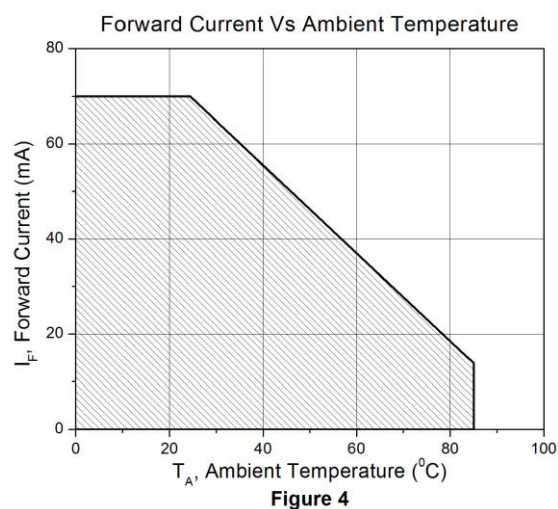
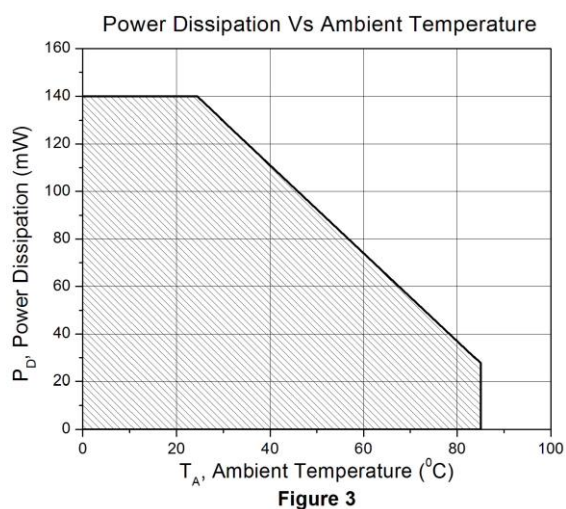
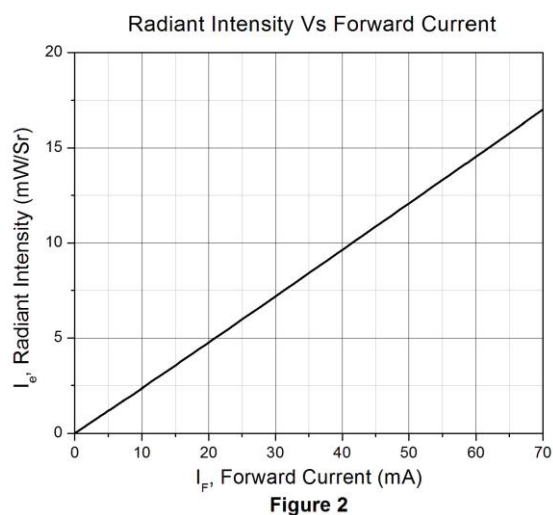
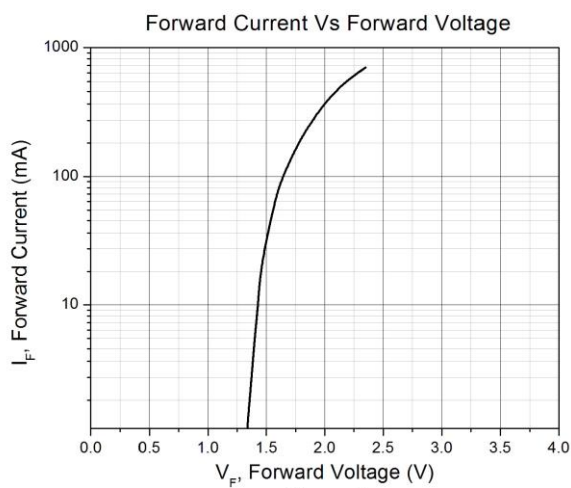
Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
V <sub>F</sub>	Forward Voltage	I <sub>F</sub> =20mA	1.30	1.45	1.7	V	
		I <sub>F</sub> =70mA	1.40	1.58	2.0		
I <sub>R</sub>	Reverse Current	V <sub>R</sub> =5V	-	-	10	μA	

#### Notes:

1. I<sub>FP</sub> Conditions--Pulse Width ≤ 100μs and Duty ≤ 1%.
2. Soldering time ≤ 5 seconds.

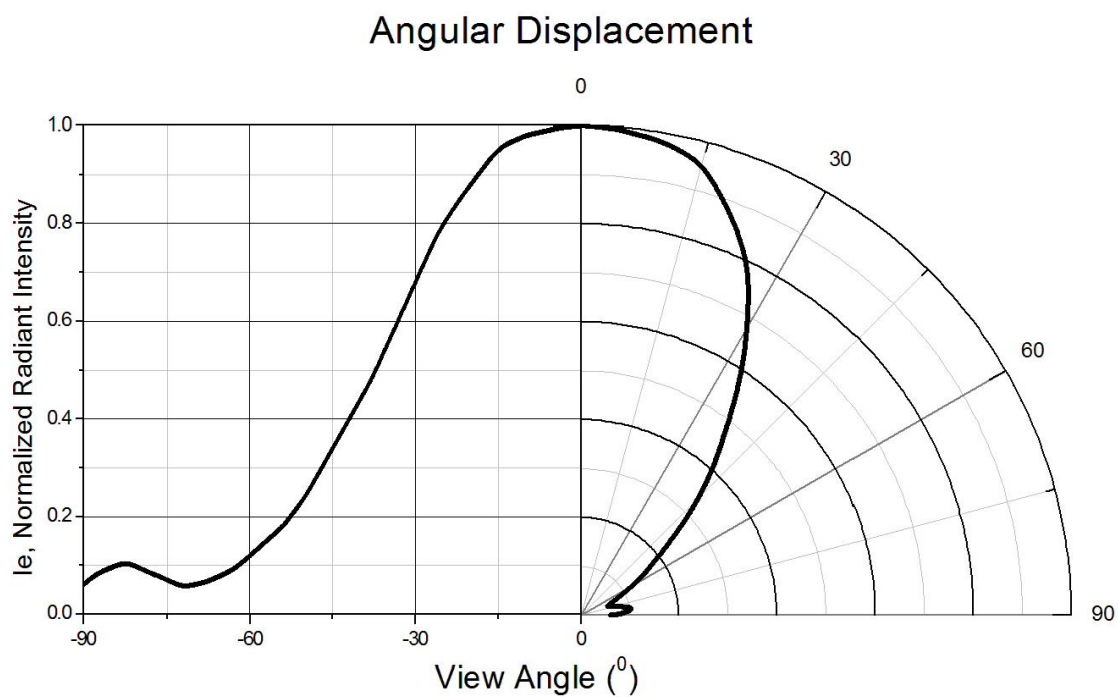


## Typical Characteristic Curves





## Typical Characteristic Curves

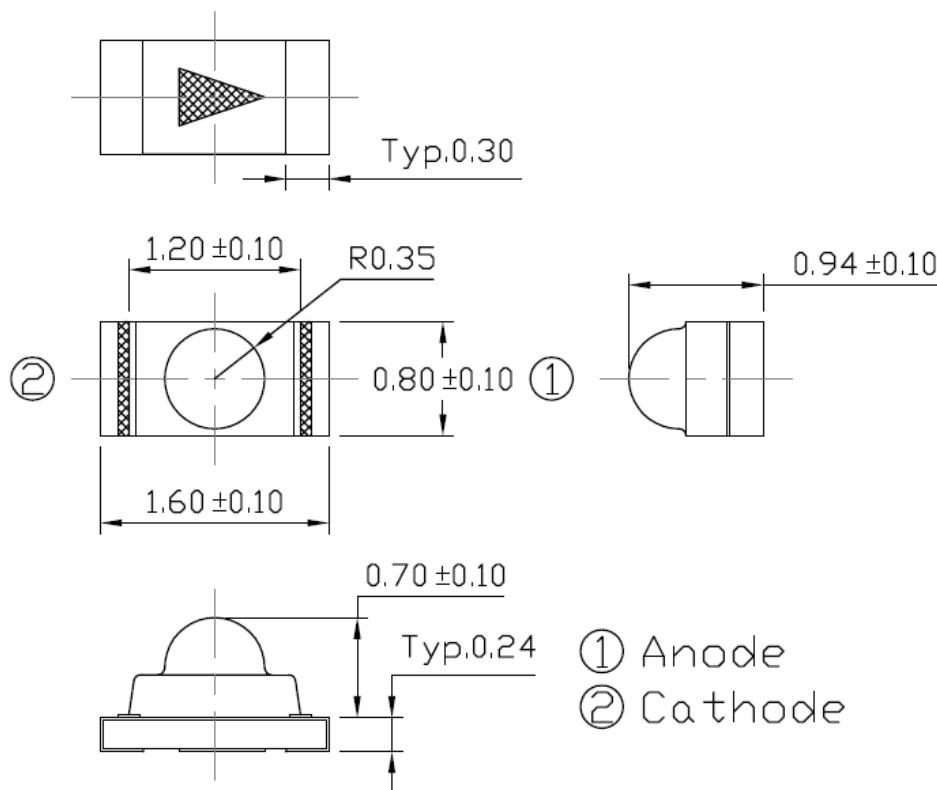




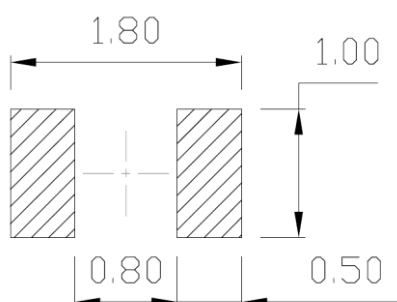
HIRP1608XC09-H5

SMD Type 800nm Infrared Emitter

### Package Dimension *All dimensions are in mm, unless otherwise stated*



### Recommended Soldering Mask *All dimensions are in mm, unless otherwise stated*



### Ordering Information

Part Number	Description	Quantity
HIRP1608XC09-H5	Tape & Reel	4000 pcs



### Reel Dimension *All dimensions are in mm, unless otherwise stated*





HIRP1608XC09-H5

SMD Type 800nm Infrared Emitter

## Label Form Specification

CT Micro  
International Corporation

MADE IN CHINA

Part no.: XXXXXXXXX  
Serial no.: XX000XX  
Lot no.: XXXXXXXXX  
Q'ty: XXXX pcs  
Date Code: 20XXXXX

Bin Code: X

Pb  
RoHS

Part no: CTM Production Number

Serial no: Production Number

Lot no: Lot number

Q'ty: Packing Quantity

Date Code: Manufacture Date

Bin Code: 1e Ranks

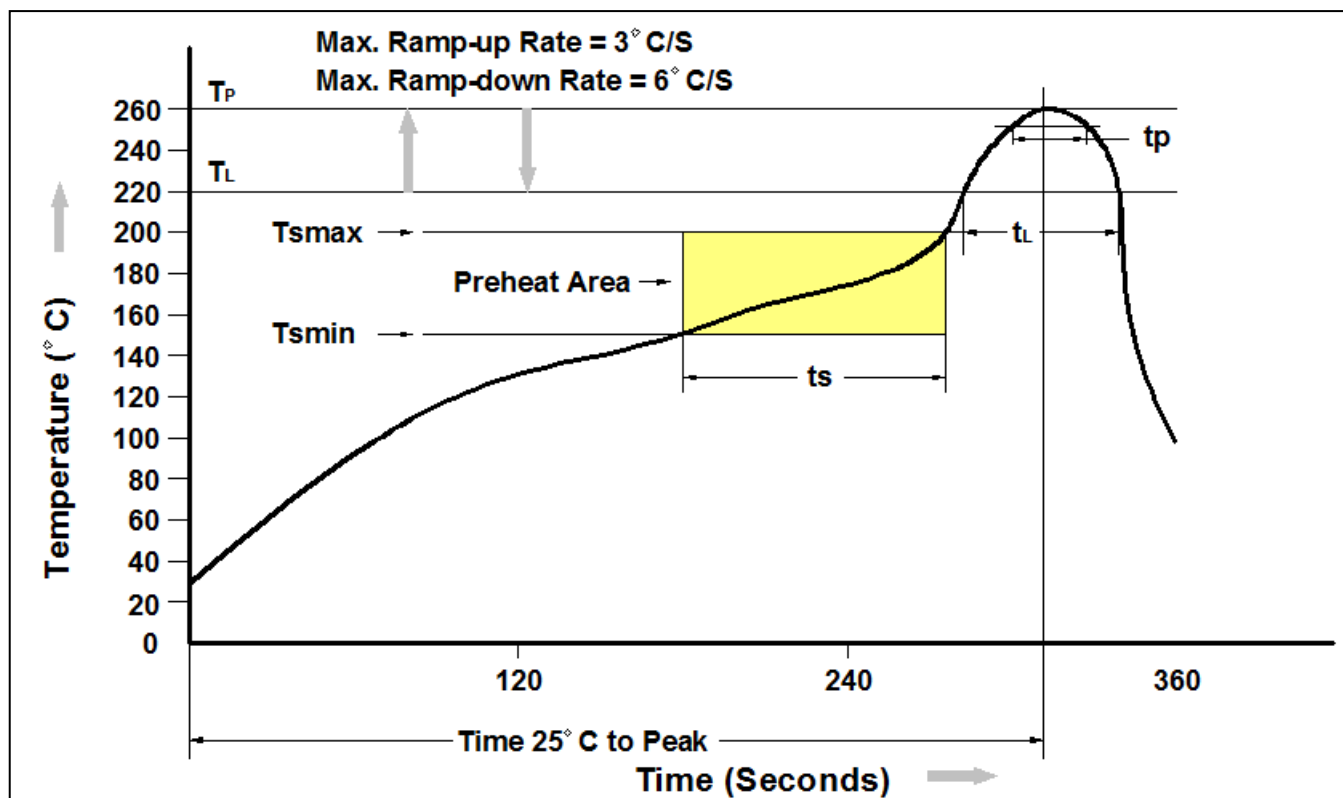
MADE IN CHINA: Production Place

## Storage Condition

1. Do not open moisture proof bag before the products are ready to use.
2. The moisture barrier bag should be stored at 30°C and 90%R.H. max. before opening.  
Shelf life of non-opened bag is 12 months after the bag sealing date.
3. After opening the moisture barrier bag floor life is 168h at 30°C/60%RH. max. Unused LEDs should be resealed into moisture barrier bag. (Refer to J-STD-020 Standard)
4. If the moisture absorbent material has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the J-STD-033 Standard conditions.



## Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t <sub>L</sub> to t <sub>P</sub> )	3°C/second max.
Liquidous Temperature (T <sub>L</sub> )	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t <sub>P</sub> ) within 5°C of 260°C	30 seconds
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.





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- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.*